



Repair Document

B10C/OT-565



Note: this manual is non-contractual and TCT Mobile phone can modify without prior notice the characteristics of described equipments.

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HISTORY			
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	Function	Name	Date	Signature
Written by	CPM	Frank		
Verified by				
Approved by				

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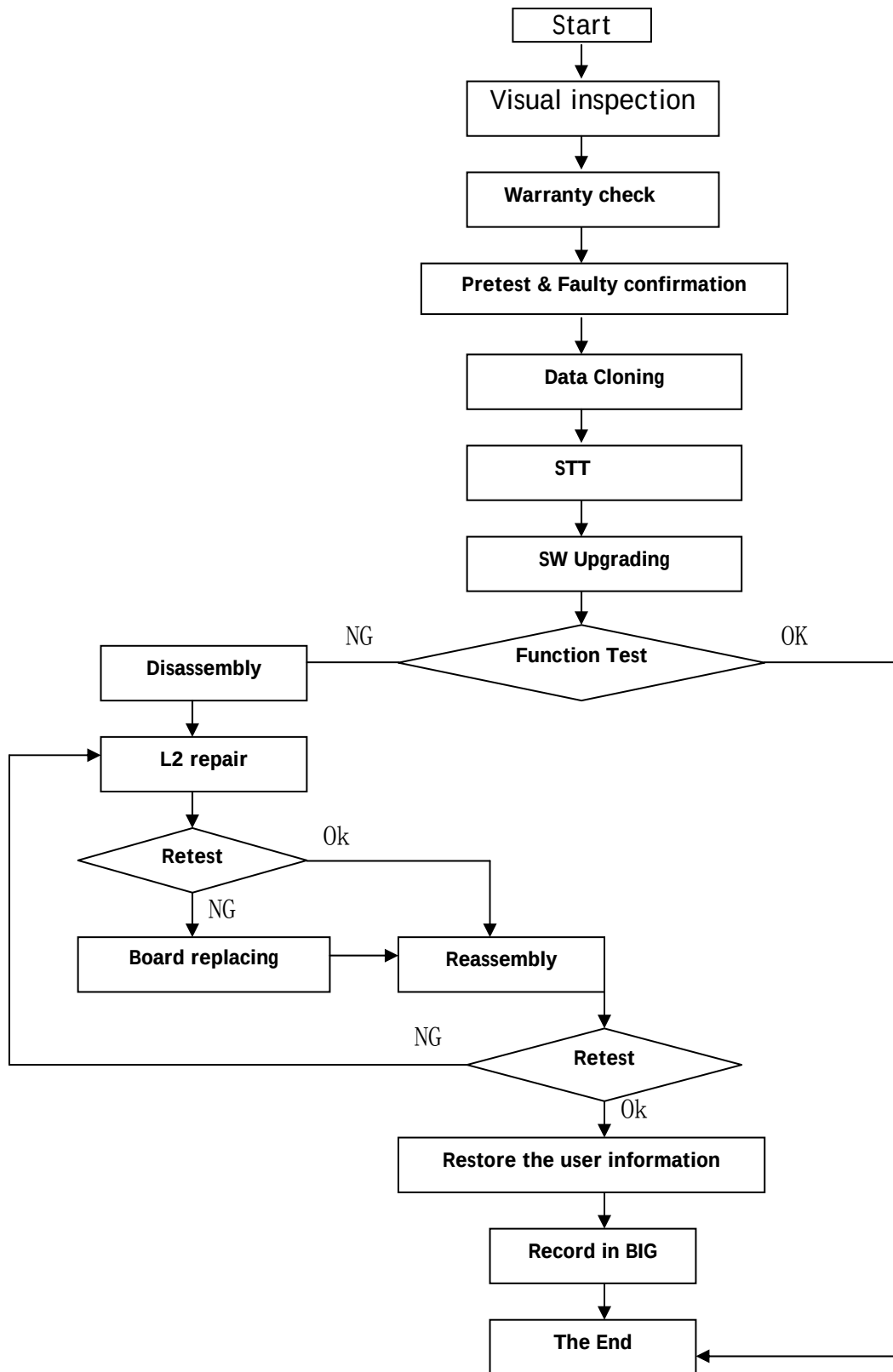
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1. LEVEL 2 REPAIR PROCESS



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2. VISUAL INSPECTION AND WARRANTY CHECK

2.1 Warranty Check

Warranty confirmation of L1:

➤ IMEI sticker check:

- 1) The IMEI number **MUST** be the same with the one on the IMEI sticker. If not, it's out of warranty policy
- 2) IMEI label should **NOT** be removed/ scratch or unreadable/ not approved or provided by Alcatel.

➤ Humidity sticker: Liquid detection on humidity sticker



sticker OK

Sticker of a good terminal
This terminal is under warranty.



sticker NOK

Sticker of a terminal dived in water
This terminal is out of warranty.

➤ Visual mechanical check;

- 1) Corrosion: corrosion on the USB connectors, SIM connectors, and other metal surfaces
- 2) Holes (diam > 1mm): Holes on any surface, including the front casing, furnished frame, battery cover, LCD Lens, keypad...
- 3) Big bumps (diam > 1mm): Bumps on any surface, including the front casing, furnished frame, battery cover, LCD Lens, keypad...
- 4) Long scratch (length > 3mm): Scratches on any surface, including the front casing, furnished frame, battery cover, LCD Lens, keypad...
- 5) Distortion: Bend, twisted or crushed on the h/s, cover/casing or connectors...
- 6) Broken: LCD broken, casing/cover broken...
- 7) Fallen off: Keypad tear off, LCD lens, connectors fallen off ...
- 8) Gap: External physical damage relating to abnormal use, like front case and frame opened
- 9) Others:
 - Damage caused by disassembly like wrong part assembly, lost of components
 - Use in abnormal environment like too high temperature with plastic melts

2.2 Pretest

- Power on the cell phone.
- Insert a battery, plug a charger on product, and check the icon on main display or sub display.
- If the cell phone asks to input NCK code, which means it's SIM locked, and can only be worked with dedicated SIM card. Use the correct SIM card.
- Enter the super code to unlock the phone if necessary.
- If power on OK, test step by step with the auto test code. Press *#2886# on the idle screen to start auto test.

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- a) **Check Traceability Information:**
Screen display the traceability information. If they are all right, press Pass to continue.
- b) **LCD display test:**
The patterns are displayed on the main screen from "COLOR" pattern, "BLACK" pattern, "CHECKER" pattern, "GREY CHART" pattern, "WHITE" pattern, "MENU" pattern, "MacBeth" pattern. If they are all right, press Pass to continue.
- c) **Sub-LCD display test:**
Display "Hello my friend!" in the sub-LCD.
Display confirm information in main LCD.
If they are all right, press Pass to continue.
- d) **Main LCD backlight test:**
The backlight will be auto on and off, if it works all right, press Pass to continue.
- e) **Keypad backlight test:**
Keypad backlights begin flashing, if it works all right, press Pass to continue.
- f) **Keypad test:**
The operator presses all keys. If all keys are pressed, go to next text item automatically. Timeout is fixed to 40s.
- g) **Vibrator test:**
Vibrator begins to work, if it works all right, press Pass to continue.
- h) **Camera Test:**
Display the Camera Screen then go to result confirm screen. If it works all right, press Pass to continue.
- i) **Camera Zoom Test:**
Display Camera zoom screen first. If it works all right, press Pass to continue.
- j) **SIM card test:**
Display "testing..." during the wait of the status.
Display "Insert SD card" if no SD card inserted
Timeout is fixed to 15s.
If pass, screen display "OK" for 1s and go to the next test item automatically.
- k) **USB charger test:**
Display "testing..." during the wait of the status.
Display "Insert USB charger" if no USB charger inserted
Timeout is fixed to 15s.
If pass, screen display "OK" for 1s and go to the next test item automatically.
- l) **SD card test:**
Display "testing..." during the wait of the status.
Display "Insert SD card" if no SD card inserted
Timeout is fixed to 15s.
If pass, screen display "OK" for 1s and go to the next test item automatically.
- m) **Bluetooth test:**
Display "searching..." during the wait of the status.
Timeout is fixed to 20s.
If pass, screen display "OK"(include BT device info and address) for 1s and go to the next test item automatically.
- n) **Audio connector test:**
Display "testing..." during the wait of the status.
Display "Insert **audio connector**", if no audio connector inserted.
Timeout is fixed to 15s.
If pass, screen display "OK" for 1s and go to the next test item automatically.
- o) **Headset left test:**
The operator does a small acoustic test, he speaks in the headset microphone and estimates the audio quality when he ears the signal in headset left earphone. If it works all right, press Pass to continue.
- p) **Headset right test:**
The operator does a small acoustic test, he speaks in the headset microphone and estimates the audio quality when he ears the signal in headset right earphone. If it works all right, press Pass to continue.
- q) **Headset test:**
The operator does a small acoustic test, he speaks in the headset microphone and estimates the audio quality when he ears the signal in headset earphone. If it works all right, press Pass to continue.
- r) **FM play test:**

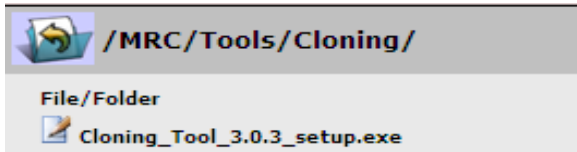
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- The default frequency is 103.6MHz (1036)
 Press "Enter" key to listen the radio.
 The input frequency number should be 4 digits.
 Delete the digit by pressing "LEFT" key.
 The range of frequency is from 0875 to 1080.
 Set next frequency by pressing "DOWN" key.
 If it works all right, press Pass to continue.
- s) **Headset unplug test:**
 Display "Remove headset", if any audio connector connected.
 Timeout is fixed to 20s.
 If pass, mini display "OK" for 1s and go to the next test item automatically.
- t) **Melody Test:**
 Play music with loud speaker. If it works all right, press Pass to continue.
- u) **Hall Test:**
 Screen display "Pls. Close Slide" and try to detect whether the slide is closed. Then, handset detector whether the slide is opened by operator.
 If pass, go to the next test item automatically.
 Total timeout is fixed to 10s for waiting.
- v) **Temperature test:**
 Screen display the handset temperature. If it is regular, press Pass to continue.
- w) **Test status memorization**
 Screen display the test status.
- Make a call.
 - Receive a call.
 - Reproduce the fault which end user complaint.

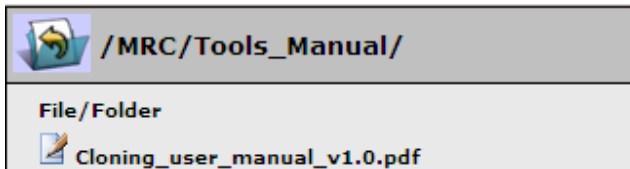
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3. CLONING TOOL (TO be updated)

- 1) Find cloning tool on MLDC as below detail location:

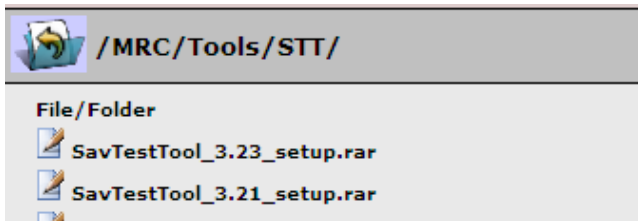


- 2) Install the cloning tool in your computer.
- 3) Follow the user manual on MLDC to upgrade the mobile.

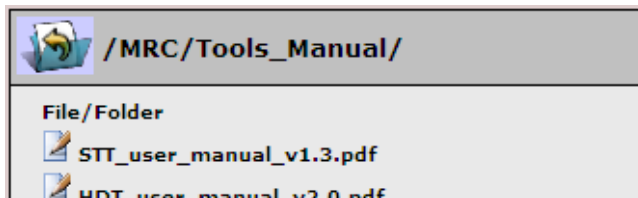


4. SAV TEST TOOL (STT)

- 1) Find STT on MLDC as below detail location:



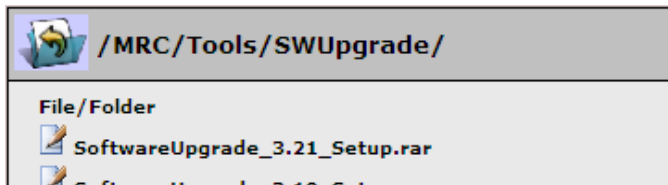
- 2) Install the cloning tool in your computer.
- 3) Follow the user manual on MLDC to upgrade the mobile.



5. SOFTWARE UPGRADING

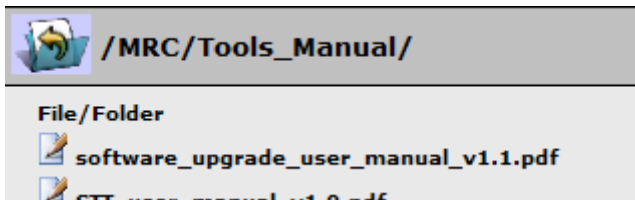
SW Upgrade tool is a method to download the SW from the SW upgrade server. Your internet connection is necessary during the process.

- 1) Find software Upgrade tool on MLDC as below detail location:



- 2) Install the cloning tool in your computer.
- 3) Follow the user manual on MLDC to upgrade the mobile.

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6. LOCAL DOWNLOADING

HDT is a tool for local software downloading in RSH. There is no need of internet connection in the downloading progress.

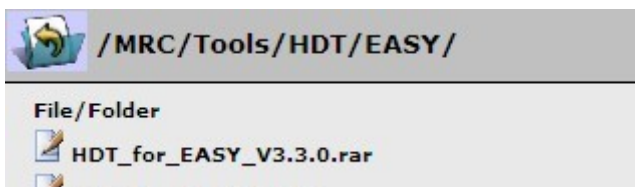
- **Notice:** from OT-565 product, common MTK bench is used on HDT. This bench supports 3 channels downloading in one time. The bench does not have a dongle inside, so insert the dongle into your computer before downloading.



There are 2 kinds of sockets which can match the bench: handset socket for handset downloading, and PCBA socket for PCBA downloading.

Steps:

- 1) Download HDT application for Easy from MLDC;



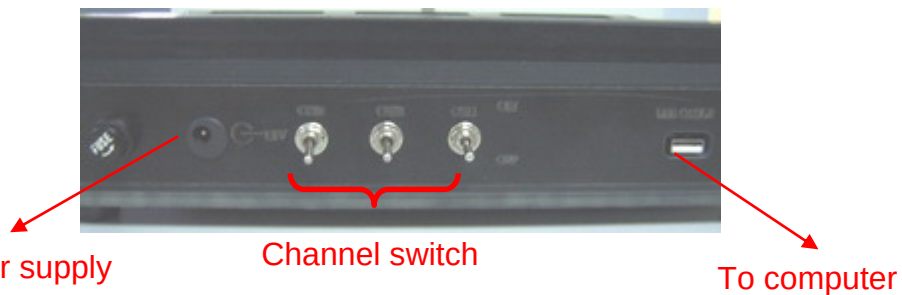
- 2) Download the SW (main code+perso+latest commercial DB) and install it under the default route;
- 3) Put the socket on the bench, and make sure they well connected to each other;
Put OT-565 PCBA onto the socket; also make sure they connected well;



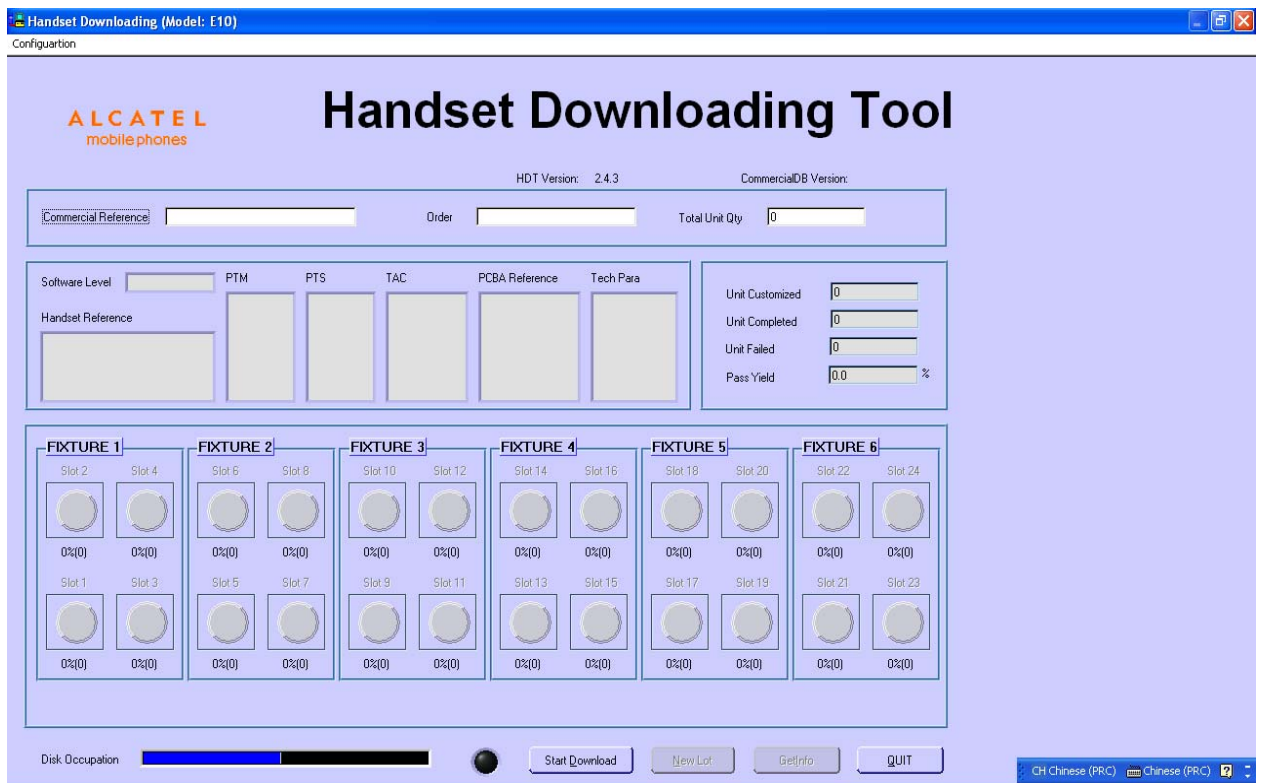
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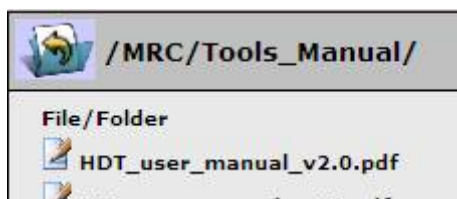
- 4) Power supply to the 12V connector; and connect to the computer with USB cable; Turn on the +12V switch, and +12V light turn red;



- 5) Create the folder “B10C” under C:\HDTE10\IMEI\Delivery, and put IMEI file on it;
6) Start HDT application by double click “HDT.exe” in the folder of C:\HDTE10\Bin;



- 7) Detail steps on the user manual which you can find in:



Notice:

- 1) The bench supports 3-channel downloading, but when you press the red button, at most 2 in one time.
- 2) Change for handset socket when you need handset downloading; and the socket can be replaced by any other module when you want to download other MTK product, without changing the bench.

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7. DISASSEMBLY and REASSEMBLY of OT-565

7.1 ESD Safety



Please wear static loop or static glove

7.2 Disassembly tools

You may use the following tools during the disassembly and reassembly procedure:

- Plastic Wedge
- Screw driver
- Tweezers
- Soldering iron
- Hot wind gun
- Soldering Jig
- Hook
- Knife

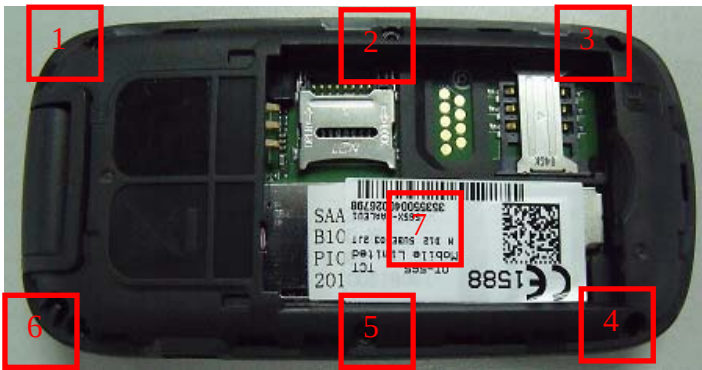
Please make reference to APPENDIX 1 and find out the pictures of the tools.

7.3 Process

The steps of disassembly OT-565 are as below.
This module should only be disassembled from bottom to top.

Step 1:
Take off the battery cover, battery and SIM card if there is.

Step 2:
Take off the 6 screws from the furnished frame, take off the commercial label 7 from the battery house, position as the below picture showed



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Step3:
Separate the furnished frame and main PBCA.



Step 4:
Take off the main FPC connector 8, separate main PBCA from the furnished keypad casing



Step 5:
Remove keypad from keypad casing

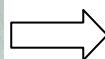
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**Step 6:**

Remove left and right cap, take off the two screws below of them

**Step 7:**

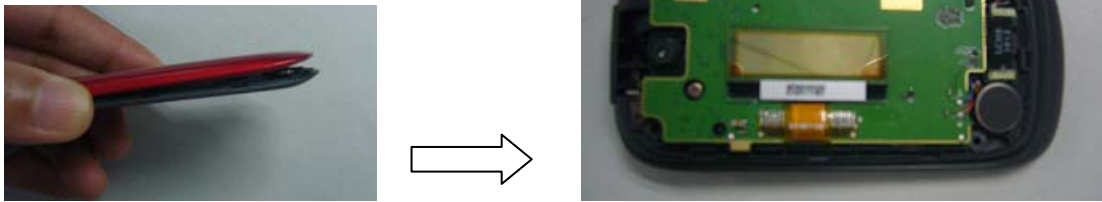
Use knife to remove main LCD lens

**Step 8:**

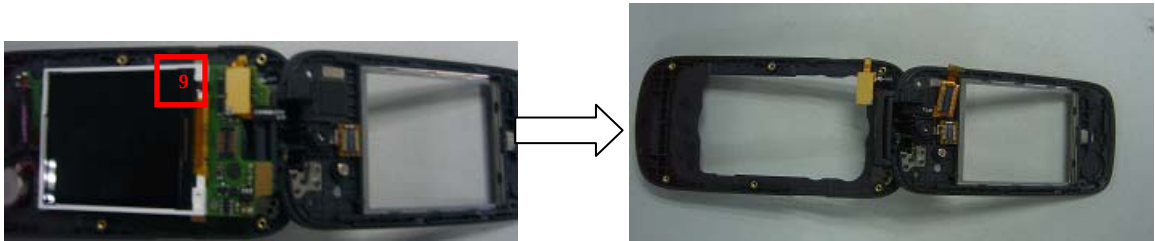
Use Plastic Wedge to break the front case and back case then remove the back casing as below picture showed

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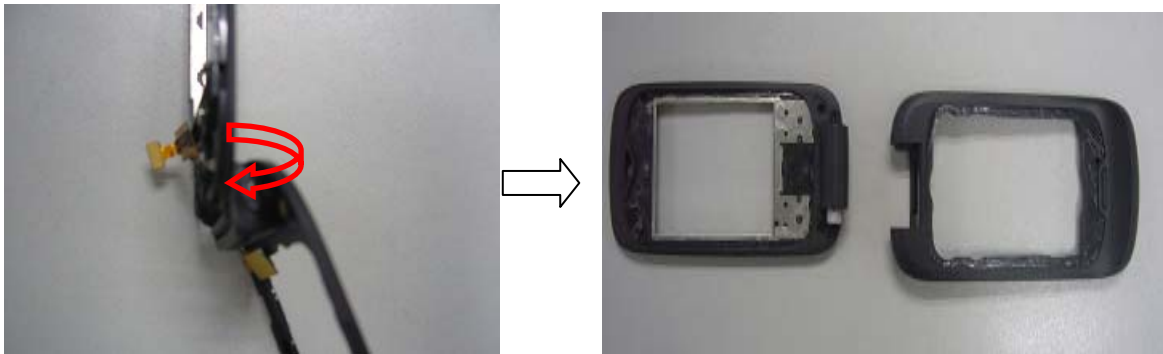
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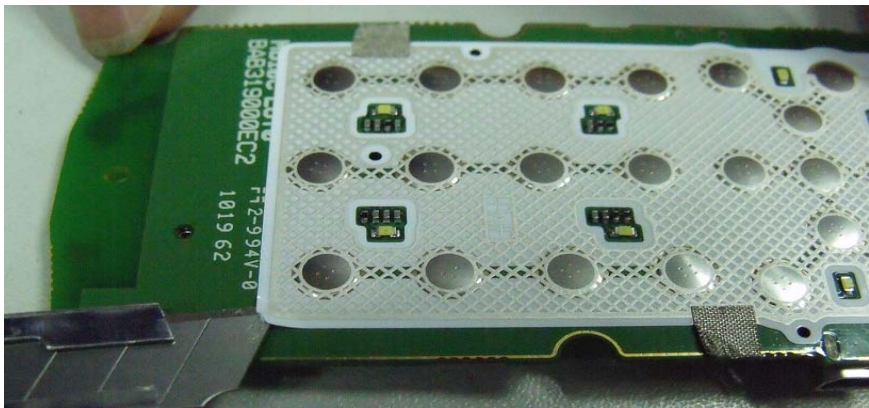
Step 9:
Turn over the flip PBCA, remove the connector 9, and then take off the LCD module and camera module



Step 10:
Use Tweezers push the hinge stopper into the house, then separate the front casing and furnished keypad casing

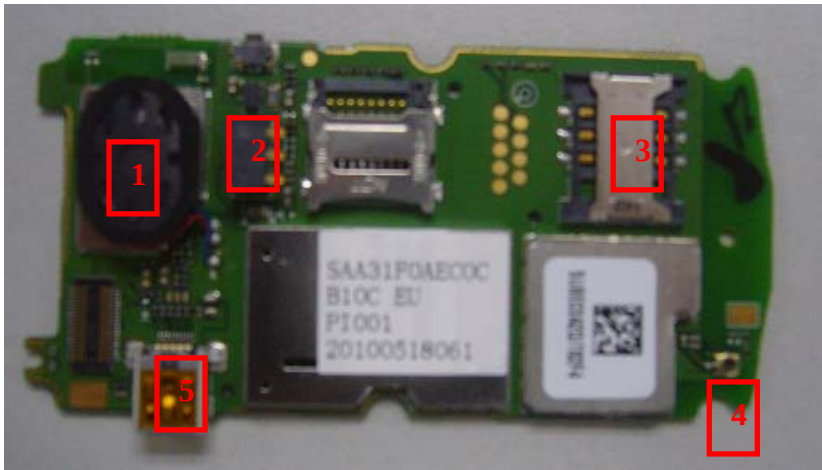


Step 11:
Use knife to take off the key film from main PBCA

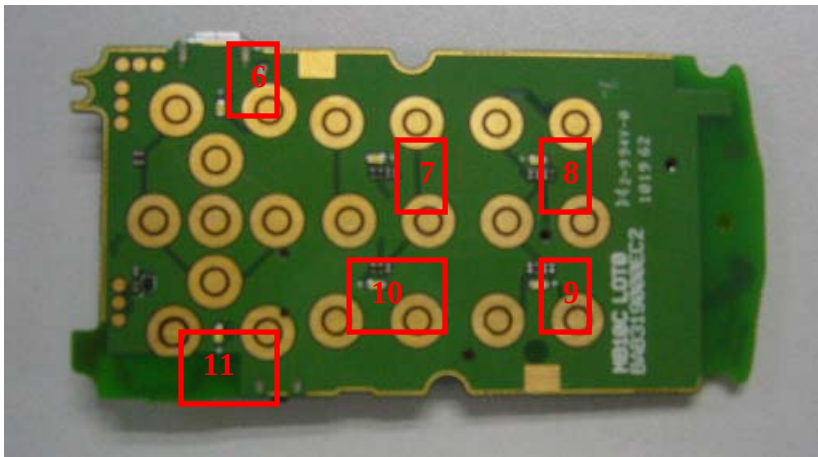


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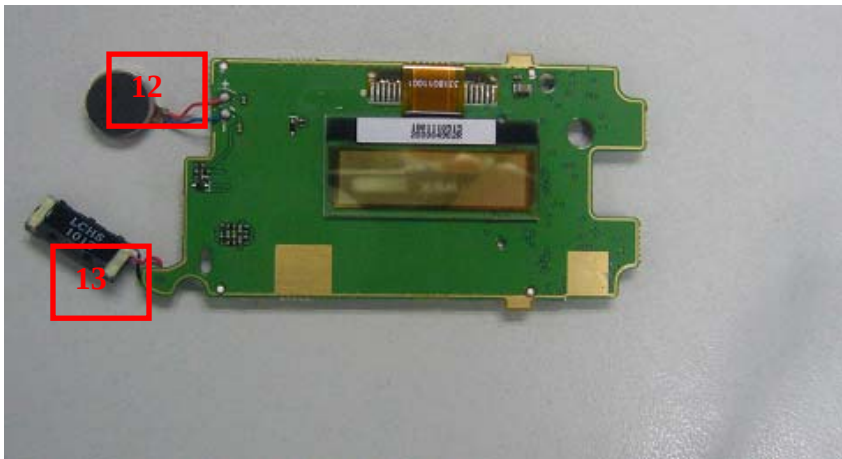
Step 12:
Remove the following components from main PCBA with hot wind gun.



1-speaker 2-battery connector 3-SIM connector 4-RF connector 5-USB connector



6, 7, 8, 9, 10, 11, 12-LED



12-vibrator 13-receiver

Disassembly Notice:

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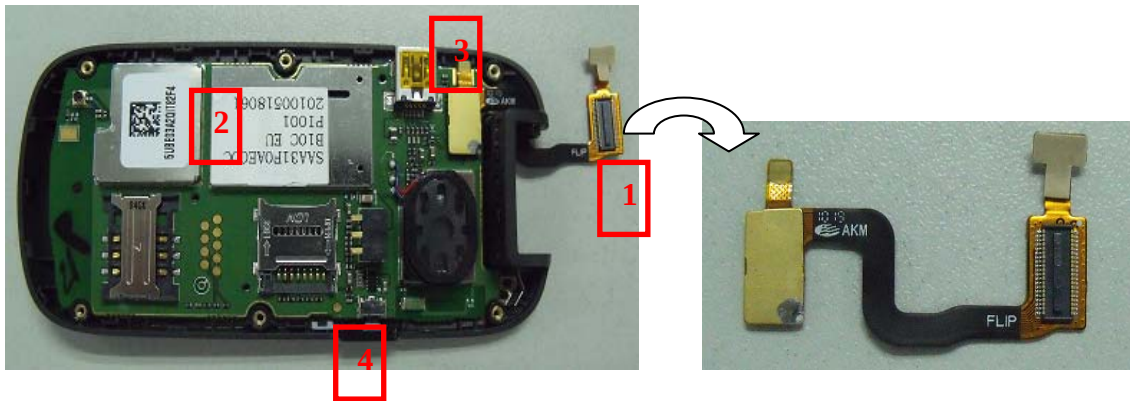
Put all the spare parts on right position (don't let all spare parts mixed and put on the clean place to avoid vitiated or stained for each spare part) after disassembly. When taking apart of LCD and key film, take care not to dirty or damage it.

7.4 Reassembly Process

Please make reference to the disassembly process for assembly reverse an order of the disassembly steps.

Attention:

- 1) Insert main FPC and assembly main PCBA with furnished keypad casing, lock the main FPC connector to PCBA connector, and then place the side key, Assembly the furnished frame. Note the orientations of the main FPC.



- 2) Assembly the front casing with furnished keypad casing



- 3) Assembly flip PBCA with the front casing, insert camera connector and main PFC connector to flip PBCA, then assembly the back casing.

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4) Lock the four screws and place the LCD lens and the right and left caps.



7.5 Disassembly process evaluation

We list the OT-565 parts disassembly time, technique levels and disassembly methods as below, for technique levels, Class 1 signifies easy to disassembly, Class 2 signifies normal to disassembly and Class 3 signifies hard to disassembly.

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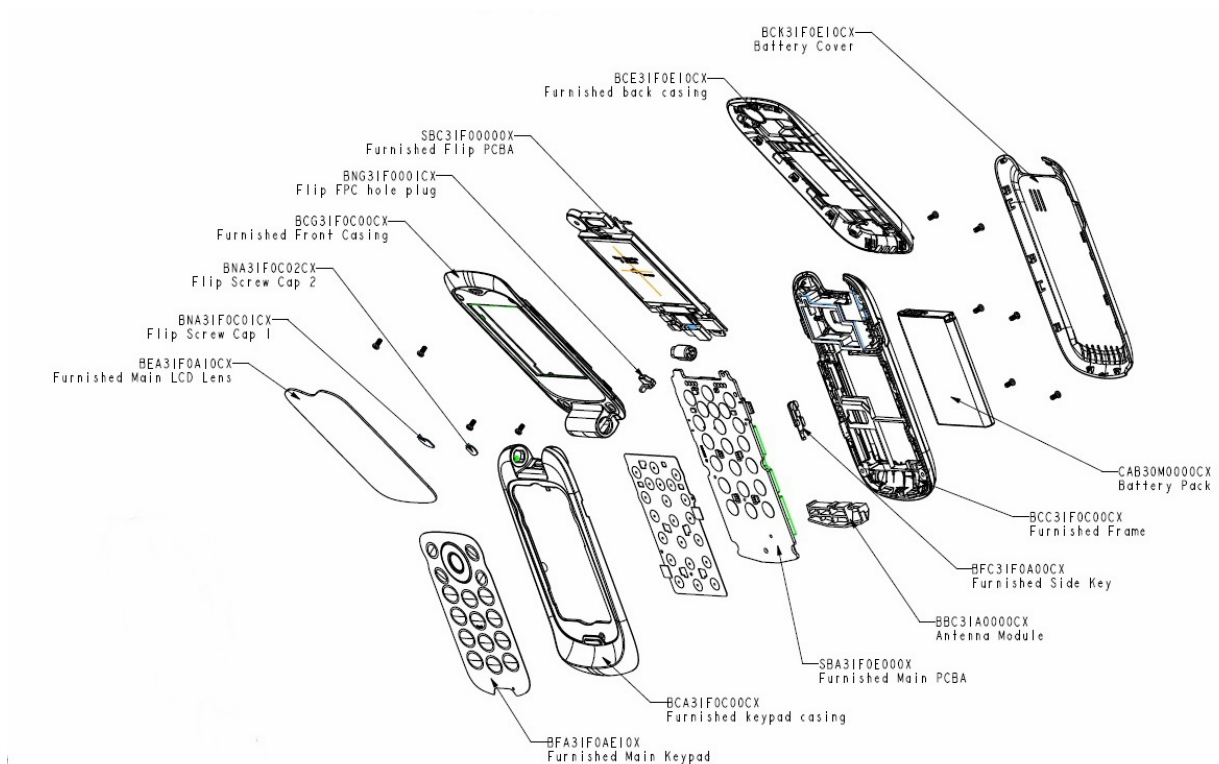
spare part	Time for disassembly	Jigs for disassembly	Difficulty Class	Remark
screw	3s	screwdriver	Class 1	
Battery cover & side key	10s	Plastic Wedge	Class 1	
Main PCBA & keypad	2s		Class 1	
Keypad casing with screws	20s	screwdriver	Class 1	
Keypad sticker	5s	Tweezers	Class 1	
Back casing	10s	Plastic Wedge	Class 2	
Hinge with screws	20s	Tweezers	Class 1	
Top keypad PCBA	1s		Class 1	
Main LCD module	3s		Class 1	
Main FPCA	5s		Class 1	
Receiver	3s	Tweezers	Class 1	
LCD Conductive Foam	1s	Tweezers	Class 1	
Top keypad	1s	Tweezers	Class 1	
panel & front casing	10s		Class 2	
Main key film	10s	Tweezers	Class 1	
Top key film	5s	Tweezers	Class 1	
camera module		Camera jig	Class 2	
vibrator	2s	Soldering jig	Class 1	
speaker	2s	Soldering jig	Class 1	
microphone	3s	hot wind gun	Class 2	easy to damage after soldering for 2 or 3 times
LED	3s	hot wind gun	Class 2	
camera socket	120s	hot wind gun	Class 3	easy to damage
USB connector	100s	hot wind gun	Class 2	easy to damage

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battery connector	80s	hot wind gun	Class 3	Plastic parts are easily damaged during heating
SIM connector	70s	hot wind gun	Class 3	Plastic parts are easily damaged during heating
RF connector	15s	hot wind gun	Class 2	
T-flash card connector	80s	hot wind gun	Class 3	Plastic parts are easily damaged during heating

7.6 Disassembly Complete



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8. LEVEL 2 REPAIR

This chapter describes the LEVEL 2 repairs that can be done without any diagnostic equipment.

	Problem description	Action And Solution
Charging	Bad or No Charge	1.Check voltage of the battery: if 0V, charge some minutes and check the charge indicator; 2.Check the battery contact, change the battery connector if broken; 3.Check the charge plug on B cover, change it if necessary;
Switch on with battery power	Can 't Switch on	1.Check voltage of the battery; 2.Check the battery contact, change the battery connector if broken; 3.Check the keypad 4.Check BTB connector socket pin
Main display and Sub display	Missing line or column; no display; bad or no LCD backlight	Check Connection flex (FPC cable),change it if necessary; Replace display module if necessary;
Keyboard	Keyboard backlight or keyboard function	Check keypad film or keypad PCB, change it if necessary
Vibrator	The vibrator does not work	Check the contact on the PCBA (dirty or oxidized), replace the vibrator if necessary;
Network Problem	No emission or No reception	Check the antenna contactor on the B cover; Check the contact on the PCBA (dirty or oxidized);
TF card	No communication between the phone and the TF card	Check the TF connector on the PCBA;
Camera	Camera doesn't work	Check camera module Check also camera FPC broken or not
Audio	Bad or no emission (TX audio from mobile); Bad or no reception (RX audio on mobile); Hands-free problem; Key beep and melody problem	Check microphone, replace it if necessary; Check the contact on the PCBA (dirty or oxidized) Check loud speaker, replace it if necessary; Check the contact on the PCBA (dirty or oxidized)

In case the LEVEL 2 repairs can't solve the problem, or if the board is damaged, exchange the board.

9. BOARD EXCHANGE

In case that LEVEL 2 repair does not solve the failure, it is mandatory to change the board and apply the following process:

- 1) Collect the fault PCBA board (without accessories LCD, vibrator, and camera), **with microphone, and key metal dome.**
- 2) Get a new PCBA from swap stock. Reuse those accessories to assemble the mobile.
- 3) Fill in the fault sticker with IMEI number, the fault code, the short code, the Hardware Technical Level, and the software version.
- 4) Send the fault PCBA with fault sticker back to L3 repair center with the suggested packaging method, the detail packaging method please see solution 1 of APPENDIX 2.

10. OTHER COMPONENT EXCHANGE

The other components exchange like *LCD module, keypad, vibrator, receiver, speaker, microphone, camera, FPC connection, audio/camera connector* and related mechanical components, please follow the detail steps from paragraph 7(Disassembly and Reassembly process), but need to be very careful to handle the components with related special tool or jig (especially replacing new components) and better to handle it with plastic tools (plastic

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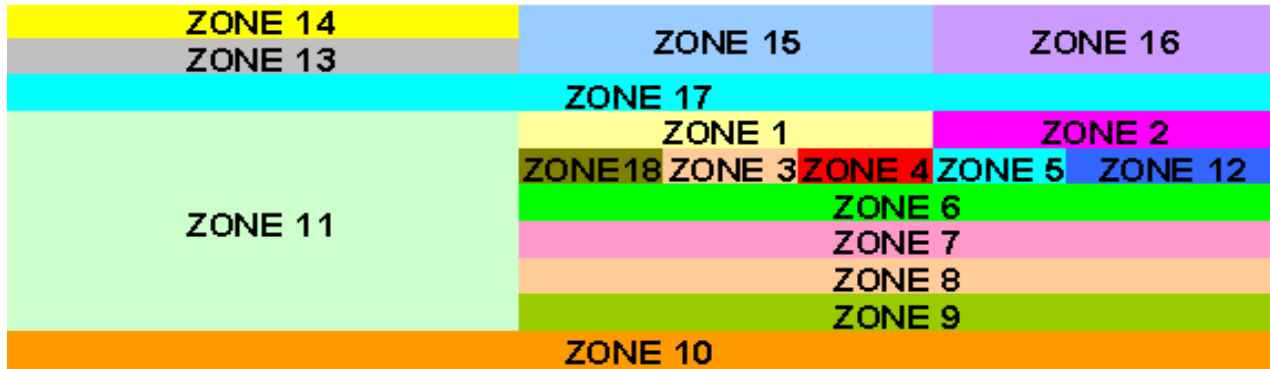
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tweezers and wedge etc.), besides technicians must put on static gloves, fingertips or wear static loop during the whole process of components exchange!

11. STICKERS

Find below the specification concerning the stickers for OT-565 products.

This sticker must be re-printed when the board is changed or upgraded .If the sticker is damaged, the mobile must be excluded of manufacturer warranty.



	Model name	Commercial name	IMEI #	FCC ID number
EU band	B10C	OT-565	35355004*****	
US band	B10CA	OT-565A	01238800 *****	RAD143

Zone	Variable	Signification
1	-	Type of product : XXXX
2	-	Distributor : For EMEA: TCT mobile limited For Latam: TCT MOBILE For CN: 苏州 TCL 天一移动通信有限公司 GSM 双频 GPRS 功能数字移动电话机
3	DATA3	PTS='soft' techn. Release xxx
4	DATA10 or DATA 12	Short code xxxxx
5	DATA2	PTM
6	-	Made In (by) ... according to made in file
7	- DATA7	Commercial Ref
8	DATA7	
9	DATA5	Full IMEI
10	DATA5	Bar code IMEI
11	DATA5/DATA11/DATA2/DATA3/DATA7	DATAMATRIX Code IMEI No. / INDUS. REF. / PTH(PTM) / PTS / COM. REF.
12	DATA4	Date Code xxx
13	-	FCC ID &CE logo
14	-	
15	Not used -	NOM mark
16	Not used	Special Logo
17		Bluetooth QD ID BXXXXXX
18	DATA18	Enhanced SIM Lock ("E"- Enhanced SIM Lock; "N" -NO Enhanced SIM Lock, including Normal SIM Lock and No SIM Lock;)

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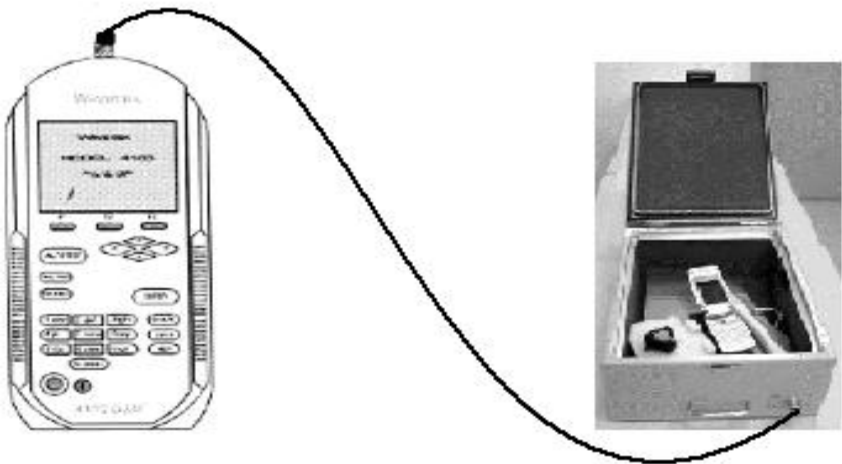
12. FINAL TEST

12.1 Function Test

During the function test, the following items must be checked and validated.

- Cosmetic aspect of the handset, the Software Technical sticker state on the Board
- Switch on the handset
- Default welcome message
- Press *#2886# on the idle screen to start the auto test (refer to the “Pretest” in Chapter 2)

12.2 Measurement



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Measurements	Channels	Power levels	Tol.min	Tol.max	Conditions
GSM					
Connection Mobile	63*	9	None	None	Radiated meas
Call base from mobile	5*	9	None	None	Radiated meas
Power level measurements	5*	9	22 dBm	28 dBm	Radiated meas
Power level measurement	5*	5	31 dBm	35 dBm	Radiated meas
Peak Phase error measurements	5*	5	0°	20°	Radiated meas
RMS Phase error measurements	5*	5	0°	5°	Radiated meas
Frequency error measurements	5*	5	-90 Hz	+90 Hz	Radiated meas
RX Level (BS power level : -60dBm)	5*	5	45	55	Radiated meas
Power level measurements	120*	5	31 dBm	35 dBm	Radiated meas
Peak Phase error measurements	120*	5	0°	20°	Radiated meas
RMS Phase error measurements	120*	5	0°	5°	Radiated meas
Frequency error measurements	120*	5	-90 Hz	+90 Hz	Radiated meas
RX Level (BS power level : -60dBm)	120*	5	45	55	Radiated meas
DCS					
Power level measurements	515*	0	28 dBm	32 dBm	Radiated meas
Peak Phase error measurements	515*	0	0°	20°	Radiated meas
RMS Phase error measurements	515*	0	0°	5°	Radiated meas
Frequency error measurements	515*	0	-180 Hz	+180 Hz	Radiated meas
RX Level (BS power level : -60dBm)	515*	0	45	55	Radiated meas
Power level measurements	880*	0	28 dBm	32 dBm	Radiated meas
Peak Phase error measurements	880*	0	0°	20°	Radiated meas
RMS Phase error measurements	880*	0	0°	5°	Radiated meas
Frequency error measurements	880*	0	-180 Hz	+180 Hz	Radiated meas
RX Level (BS power level : -60dBm)	880*	0	45	55	Radiated meas
Keyboard test (1)	-	-	-	-	-
Audio test GSM	70*	9	None	None	Radiated meas
Hang up	70*	9	None	None	Radiated meas
Call mobile from BS	700*	9	None	None	Radiated meas
Power level measurements	700*	0	27 dBm	33 dBm	Radiated meas
Audio test DCS	700*	0	None	None	Radiated meas
Hang up	70*	9	None	None	Radiated meas
PCS					
Connection Mobile	661*	5	None	None	Radiated meas
Call base from mobile	513*	5	None	None	Radiated meas
Power level measurements	513*	5	15 dBm	25 dBm	Radiated meas
Power level measurements	513*	0	25 dBm	35 dBm	Radiated meas
Peak Phase error measurement	513*	0	0°	20°	Radiated meas
RMS Phase error measurements	513*	0	0°	6°	Radiated meas
Frequency error measurements	513*	0	-180 Hz	+180 Hz	Radiated meas

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RX Level (BS power level : -65dBm)	513*	0	35	55	Radiated meas
Keyboard test (1)	-	-	-	-	-
Power level measurements	880*	0	25 dBm	35 dBm	Radiated meas
Peak Phase error measurements	880*	0	0°	20°	Radiated meas
RMS Phase error measurements	880*	0	0°	6°	Radiated meas
Frequency error measurements	880*	0	-180 Hz	+180 Hz	Radiated meas
RX Level (BS power level : -60dBm)	880*	0	35	55	Radiated meas
Audio test 1900	683*	5	None	None	Radiated meas
Hang up	683*	5	None	None	Radiated meas
Call mobile from BS	683*	5	None	None	Radiated meas
Power level measurements	683*	5	15 dBm	25 dBm	Radiated meas
Hang up	683*	5	None	None	Radiated meas

- These values are given for indication , compatible low ,middle and high channels have to be found.

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APPENDIX 1 Tools and Equipments for L2 Repair Center

➤ Repair Tools and Downloading Tools:



Plastic Stick



Tweezers



Hot wind gun



Screwdriver (TORX6)



Soldering iron



Camera Jig



Knife

➤ Other Mandatory Equipments

- 1) Final test kit (charger, batteries, Back covers)
- 2) Final test interface
- 3) Bench and socket
- 4) Stickers

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APPENDIX 2 Packaging Requirements

➤ **PCBA shipment requirement:**

- 1) Against Electro-Static.
- 2) Avoid PCBA are laid to overlap each other.
- 3) Against press outside package.

- **Solution 1:** Each PCBA is packaged by shielding bag, put each PCBA into each cave of the carton (see picture below).



- **Solution 2:** Stack by special trays (15 trays maximum), put empty trays to fill space inside the carton and all trays should be bound tightly in order to avoid PCBA move out (see picture below).



End of the document

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